Surface Mount Schottky Power Rectifier

SMB Power Surface Mount Package

These devices employ the Schottky Barrier principle in a metal-to-silicon power rectifier. Features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for low voltage, high frequency switching power supplies; free wheeling diodes and polarity protection diodes.

Features

- Compact Package with J-Bend Leads Ideal for Automated Handling
- Highly Stable Oxide Passivated Junction
- Guard-Ring for Overvoltage Protection
- Low Forward Voltage Drop
- ESD Ratings:
 - ♦ Human Body Model = 3B (> 16000 V)
 - Machine Model = C (> 400 V)
- NRVB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- All Packages are Pb-Free*

Mechanical Characteristics

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 95 mg (Approximately)
- Cathode Polarity Band
- Maximum Temperature of 260°C/10 Seconds for Soldering
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable



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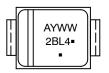
http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 2.0 AMPERES, 40 VOLTS



SMB CASE 403A

MARKING DIAGRAM



2BL4 = Specific Device Code A = Assembly Location

Y = Year WW = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------------|------------------|------------------------|
| MBRS240LT3G | SMB (Pb-Free) | 2,500 / Tape & Reel |
| NRVBS240LT3G | SMB (Pb-Free) | 2,500 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit | |
|---|--|-------------|------|--|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 40 | V | |
| Average Rectified Forward Current (At Rated V _R , T _C = 100°C) | I _O | 2.0 | А | |
| Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _C = 105°C) | I _{FRM} | 4.0 | А | |
| Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz) | I _{FSM} | 25 | А | |
| Storage Temperature | T _{stg} , T _C | -55 to +150 | °C | |
| Operating Junction Temperature | TJ | -55 to +150 | °C | |
| Voltage Rate of Change (Rated V_R , $T_J = 25$ °C) | dv/dt | 10,000 | V/µs | |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit | |
|--|---|----------|------|--|
| Thermal Resistance, Junction-to-Lead (Note 1) Thermal Resistance, Junction-to-Ambient (Note 2) | $egin{aligned} R_{	hetaJL} \ R_{	hetaJA} \end{aligned}$ | 18 78 | °C/W | |

^{1.} Mounted with minimum recommended pad size, PC Board FR4.

ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Value | | Unit |
|--|----------------|-----------------------|------------------------|------|
| Maximum Instantaneous Forward Voltage (Note 3) | V _F | T _J = 25°C | T _J = 125°C | V |
| see Figure 2 (I _F = 2.0 A) (I _F = 4.0 A) | | 0.43 0.54 | 0.375 0.55 | |
| Maximum Instantaneous Reverse Current (Note 3) | I _R | T _J = 25°C | T _J = 100°C | mA |
| see Figure 4 (V _R = 40 V) (V _R = 20 V) | | 2.0 0.5 | 60 40 | |

^{3.} Pulse Test: Pulse Width \leq 250 μ s, Duty Cycle \leq 2.0%.

^{2. 1} inch square pad size (1 x 0.5 inch for each lead) on FR4 board.

TYPICAL CHARACTERISTICS

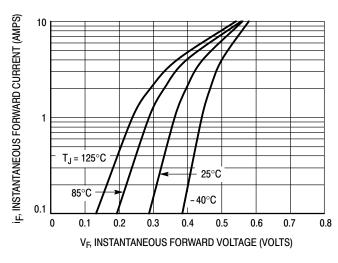


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

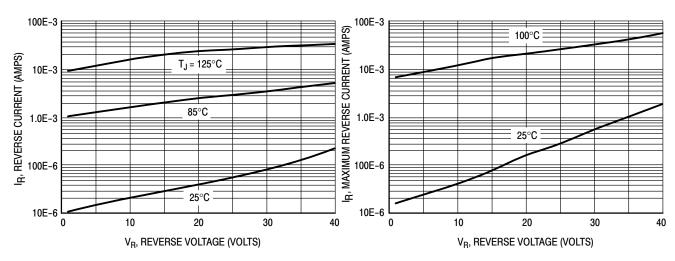
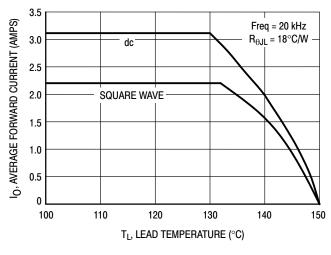


Figure 3. Typical Reverse Current

Figure 4. Maximum Reverse Current

TYPICAL CHARACTERISTICS



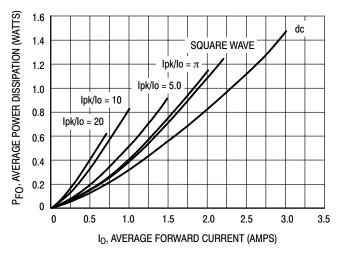
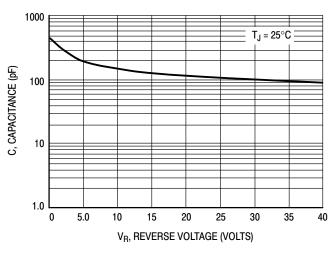


Figure 5. Current Derating

Figure 6. Forward Power Dissipation



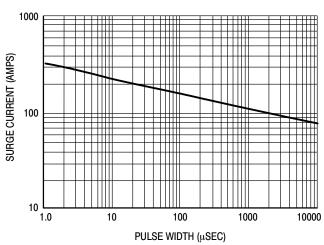


Figure 7. Capacitance

Figure 8. Maximum Non-Repetitive Forward Surge Current

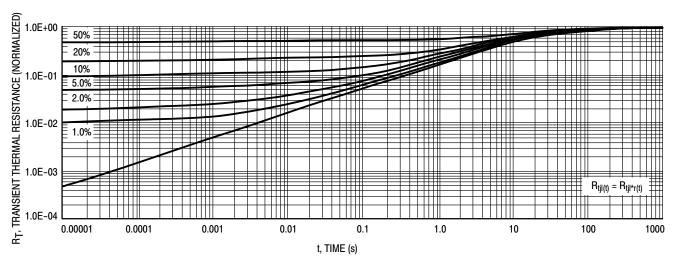
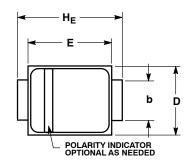
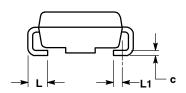


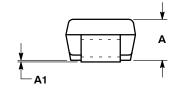
Figure 9. Thermal Response

PACKAGE DIMENSIONS

SMB CASE 403A-03 **ISSUE H**



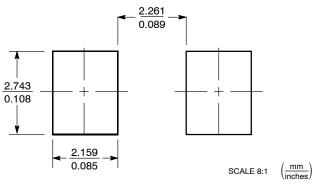




- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 D DIMENSION SHALL BE MEASURED WITHIN DIMENSION P.

| | MILLIMETERS | | | INCHES | | | |
|-----|-------------|----------|------|--------|-----------|-------|--|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX | |
| Α | 1.90 | 2.20 | 2.28 | 0.075 | 0.087 | 0.090 | |
| A1 | 0.05 | 0.10 | 0.19 | 0.002 | 0.004 | 0.007 | |
| b | 1.96 | 2.03 | 2.20 | 0.077 | 0.080 | 0.087 | |
| С | 0.15 | 0.23 | 0.31 | 0.006 | 0.009 | 0.012 | |
| D | 3.30 | 3.56 | 3.95 | 0.130 | 0.140 | 0.156 | |
| E | 4.06 | 4.32 | 4.60 | 0.160 | 0.170 | 0.181 | |
| HE | 5.21 | 5.44 | 5.60 | 0.205 | 0.214 | 0.220 | |
| L | 0.76 | 1.02 | 1.60 | 0.030 | 0.040 | 0.063 | |
| L1 | | 0.51 REF | | | 0.020 REF | | |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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